

具有可控接通功能的 TPS22930 超小型、低导通电阻负载开关

1 特性

- 集成型单通道负载开关
- 超小型 4 端子晶圆芯片级封装 (显示了标称尺寸 - 详情请见附录)
 - 0.9mm × 0.9mm, 0.5mm 间距, 0.5mm 高度 (YZV)
- 输入电压范围: 1.4V 至 5.5V
- 超低 R_{ON} 导通电阻
 - $V_{IN} = 5V$ 时, $R_{ON} = 35m\Omega$
 - $V_{IN} = 3.6V$ 时, $R_{ON} = 36m\Omega$
 - $V_{IN} = 1.8V$ 时, $R_{ON} = 49m\Omega$
- 2A 最大持续开关电流
- 低静态电流 (小于 3 μA)
- 低控制输入阈值支持使用 1.2V/1.8V/2.5V/3.3V 逻辑
- 受控压摆率
- 欠压锁定
- 禁用时, 反向电流保护

2 应用

- 智能手机/无线手持终端
- 便携式工业/医疗设备
- 便携式媒体播放器
- 销售点终端
- GPS 导航设备
- 数码相机
- 便携式仪表

3 说明

TPS22930 是一款小型、低 R_{ON} 负载开关, 具有可控导通功能。此器件包括一个 P 沟道 MOSFET, 可在 1.4V 至 5.5V 的输入电压范围内运行。此开关由一个开/关输入 (ON) 控制, 此输入能够与低压控制信号直接相连。TPS22930 高电平使能。

TPS22930 器件通过在反向电压 (也称为反向电流) 情况下禁用体二极管来提供电路断路器功能。只有当电源开关被禁用时 (关闭) 反向电流保护才被激活。当输出电压 (V_{OUT}) 被驱动至高于输入 (V_{IN}) 时, 此器件释放体二极管来停止流向开关输入一侧的电流。此外, 如果此输入电压过低, 欠压锁定 (UVLO) 保护会将此开关关闭。

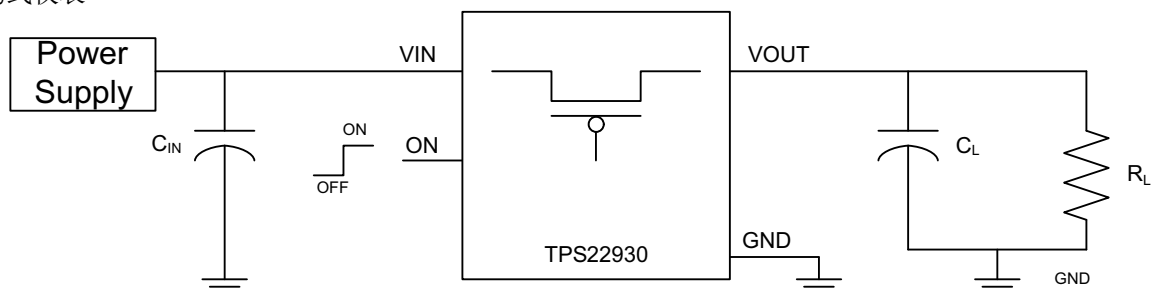
为了避免涌入电流, 此器件的转换率由内部控制。

TPS22930 采用超小型、节省空间的 4 引脚 CSP 封装并可在 -40°C 至 85°C 的自然通风温度范围内运行。

器件信息⁽¹⁾

器件型号	封装	封装尺寸 (最大值)
TPS22930	DSBGA (4)	0.92mm × 0.92mm

(1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。



简化版原理图



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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision C (January 2021) to Revision D (July 2021)	Page
• Updated $I_{RCP(Leak)}$ spec to 2.6 μA	5
Changes from Revision B (February 2016) to Revision C (January 2021)	Page
• 更新了整个文档中的表格、图和交叉参考的编号格式.....	1
Changes from Revision A (June 2015) to Revision B (February 2016)	Page
• 更改了 引脚配置和功能	1
Changes from Revision * (November 2012) to Revision A (June 2015)	Page
• 删除了“订购信息”表.....	1
• 添加了“ESD 等级”表、“特性说明”部分、“器件功能模式”、“应用和实施”部分、“电源相关建议”部分、“布局”部分、“器件和文档支持”部分以及“机械、封装和可订购信息”部分.....	1

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)^{(1) (2)}

		MIN	MAX	UNIT
V _{IN}	Input voltage	– 0.3	6	V
V _{OUT}	Output voltage	– 0.3	6	V
V _{ON}	Input voltage	– 0.3	6	V
I _{MAX}	Maximum continuous switch current		2	A
I _{PLS}	Maximum pulsed switch current, pulse ≤ 1ms, 25% duty cycle		2.5	A
T _A	Operating free-air temperature ⁽³⁾	– 40	85	°C
T _J	Maximum junction temperature		150	°C
T _{stg}	Storage temperature	– 65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.
- (3) In applications where high power dissipation and/or poor package thermal resistance is present, the maximum ambient temperature may have to be derated. Maximum ambient temperature [T_{A(max)}] is dependent on the maximum operating junction temperature [T_{J(max)}], the maximum power dissipation of the device in the application [P_{D(max)}], and the junction-to-ambient thermal resistance of the part/package in the application (R_{θJA}), as given by the following equation: T_{A(max)} = T_{J(max)} – (R_{θJA} × P_{D(max)})

5.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{IN}	Input voltage range		1.4	5.5	V
V _{ON}	ON voltage range		0	5.5	V
V _{OUT}	Output voltage range		0	V _{IN}	V
V _{IH}	High-level input voltage, ON	V _{IN} = 3.61 V to 5.5 V	1.1	5.5	V
		V _{IN} = 1.4 V to 3.6 V	1.1	5.5	
V _{IL}	Low-level input voltage, ON	V _{IN} = 3.61 V to 5.5 V	0	0.6	V
		V _{IN} = 1.4 V to 3.6 V	0	0.4	
C _{IN}	Input capacitor		1 ⁽¹⁾		μF

- (1) Refer to *Application Information* section.

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS22930	UNIT
		YZV (DSBGA)	
		4 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	189.1	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	1.9	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	36.8	°C/W
ψ_{JT}	Junction-to-top characterization parameter	11.3	°C/W
ψ_{JB}	Junction-to-board characterization parameter	36.8	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	–	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

5.5 Electrical Characteristics

Unless otherwise note, the specification in the following table applies over the operating ambient temperature $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ (Full). Typical values are for $T_A = 25^{\circ}\text{C}$.

PARAMETER		TEST CONDITIONS		T _A	MIN	TYP	MAX	UNIT
POWER SUPPLIES AND CURRENTS								
I _{IN}	Quiescent current	I _{OUT} = 0 V, V _{IN} = V _{ON} = 5.25 V	Full		2.3	10	μA	
		I _{OUT} = 0 V, V _{IN} = V _{ON} = 4.2 V			2.2	7		
		I _{OUT} = 0 V, V _{IN} = V _{ON} = 3.6 V			2.1	7		
		I _{OUT} = 0 V, V _{IN} = V _{ON} = 2.5 V			1.0	5		
		I _{OUT} = 0 V, V _{IN} = V _{ON} = 1.5 V			0.8	5		
I _{IN(off)}	Off supply current	V _{OUT} = Open, V _{IN} = 5.25 V, V _{ON} = 0 V	Full		0.3	10	μA	
		V _{OUT} = Open, V _{IN} = 4.2 V, V _{ON} = 0 V			0.2	7		
		V _{OUT} = Open, V _{IN} = 3.6 V, V _{ON} = 0 V			0.2	7		
		V _{OUT} = Open, V _{IN} = 2.5 V, V _{ON} = 0 V			0.1	5		
		V _{OUT} = Open, V _{IN} = 1.5 V, V _{ON} = 0 V			0.1	5		
I _{IN(leak)}	Leakage current	V _{OUT} = 0 V, V _{IN} = 5.25 V, V _{ON} = 0 V	Full		0.8	10	μA	
		V _{OUT} = 0 V, V _{IN} = 4.2 V, V _{ON} = 0 V			0.2	7		
		V _{OUT} = 0 V, V _{IN} = 3.6 V, V _{ON} = 0 V			0.2	7		
		V _{OUT} = 0 V, V _{IN} = 2.5 V, V _{ON} = 0 V			0.1	5		
		V _{OUT} = 0 V, V _{IN} = 1.5 V, V _{ON} = 0 V			0.1	5		
I _{ON}	ON pin input leakage current	V _{ON} = 5.5 V	Full			0.5	μA	
I _{RCP(leak)}	Reverse leakage current	V _{IN} = V _{ON} = GND, V _{OUT} = 5 V, measured from V _{IN}	Full			2.6		
UVLO	Undervoltage lockout	V _{IN} increasing, V _{ON} = 3.6 V, I _{OUT} = - 100 mA	Full			1.2		
		V _{IN} decreasing, V _{ON} = 3.6 V, I _{OUT} = - 100 mA			0.5			
RESISTANCE CHARACTERISTICS								
R _{ON}	ON-state resistance	I _{OUT} = - 200 mA	V _{IN} = 5.0 V	25°C		35	44	m Ω
				Full			50	
			V _{IN} = 4.2 V	25°C		35	44	
				Full			50	
			V _{IN} = 3.6 V	25°C		36	44	
				Full			50	
			V _{IN} = 2.5 V	25°C		39	44	
				Full			50	
			V _{IN} = 1.8 V	25°C		49	55	
				Full			62	
			V _{IN} = 1.5 V	25°C		59	66	
				Full			74	

5.6 Switching Characteristics

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IN} = 5.5 V, T _A = 25°C (unless otherwise noted)						
t _{ON}	Turn-on time	R _L = 10 Ω , C _L = 0.1 μF	4.8		μs	
t _{OFF}	Turn-off time		6.3			
t _R	V _{OUT} rise time		5.6			
t _F	V _{OUT} fall time		2.8			
V _{IN} = 4.2 V, T _A = 25°C (unless otherwise noted)						
t _{ON}	Turn-on time	R _L = 10 Ω , C _L = 0.1 μF	5.8		μs	
t _{OFF}	Turn-off time		7.3			
t _R	V _{OUT} rise time		5.4			
t _F	V _{OUT} fall time		2.8			
V _{IN} = 3.0 V, T _A = 25°C (unless otherwise noted)						
t _{ON}	Turn-on time	R _L = 10 Ω , C _L = 0.1 μF	7.4		μs	
t _{OFF}	Turn-off time		9.5			
t _R	V _{OUT} rise time		6.3			
t _F	V _{OUT} fall time		2.9			

5.7 Typical Characteristics

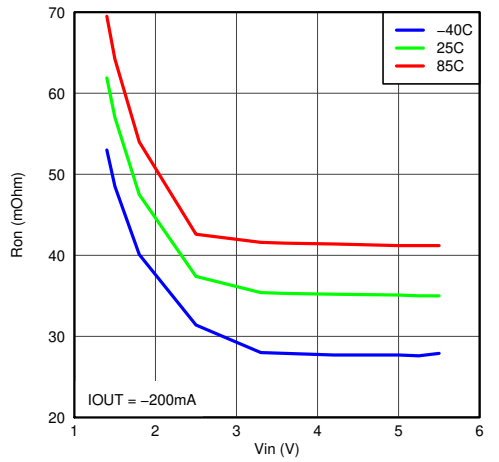


图 5-1. R_{ON} vs V_{IN}

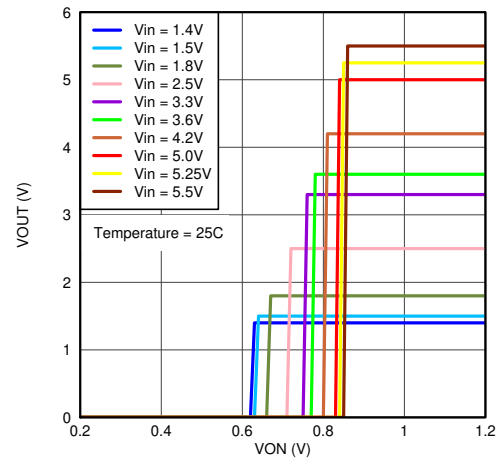


图 5-2. On Input Threshold

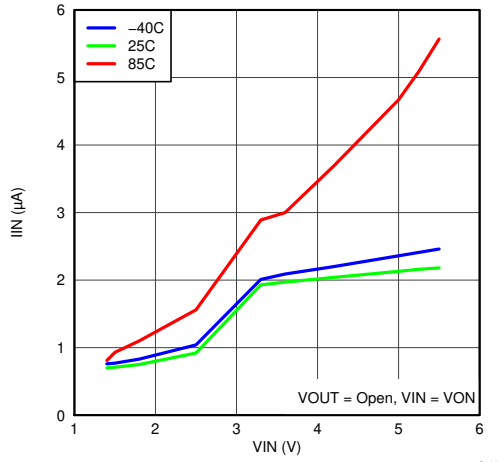


图 5-3. I_{IN} vs V_{IN}

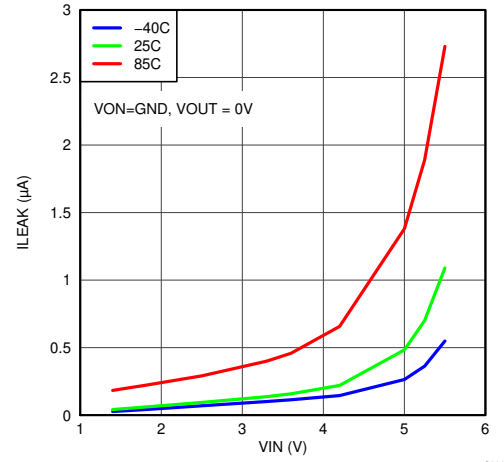


图 5-4. $I_{IN(LEAK)}$ vs V_{IN}

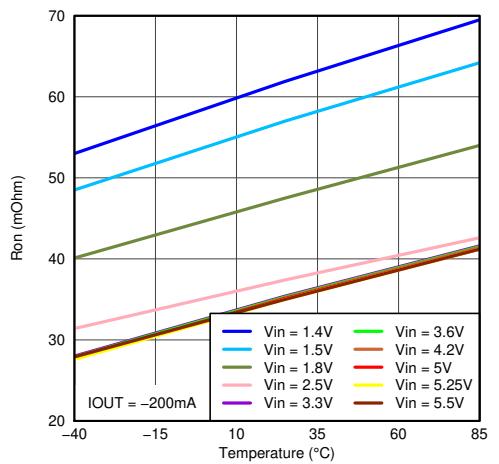


图 5-5. Temperature vs R_{ON}

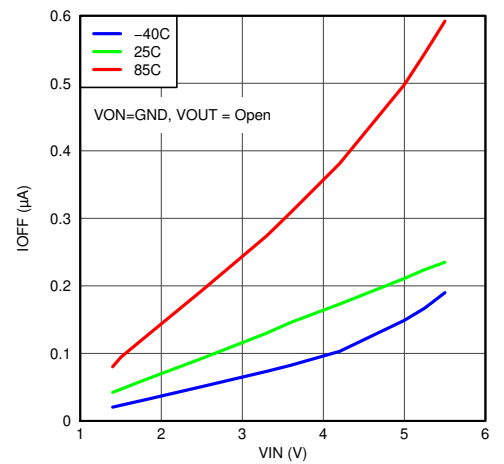


图 5-6. $I_{IN(OFF)}$ vs V_{IN}

5.7 Typical Characteristics (continued)

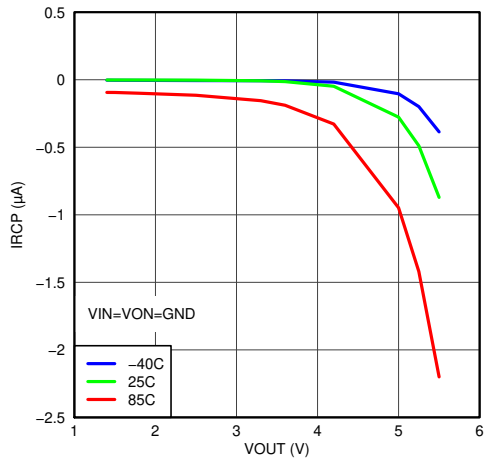


图 5-7. $I_{RCP(Leak)}$ vs V_{OUT} (Measured On VIN)

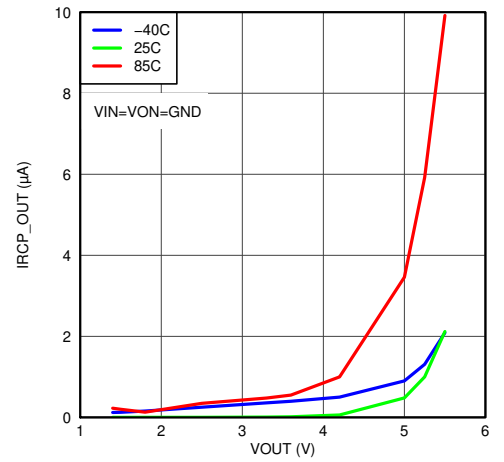


图 5-8. $I_{RCP(Leak)}$ vs V_{OUT} (Measured on VOUT)

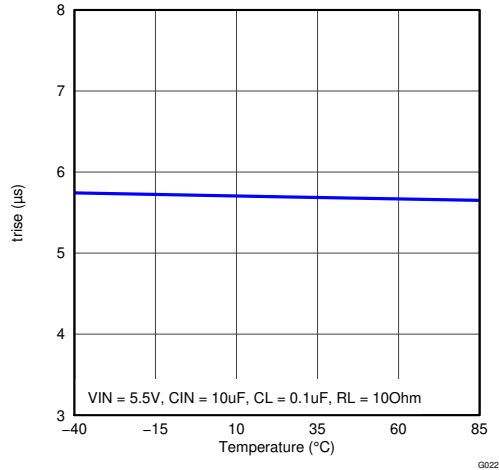


图 5-9. t_R vs Temperature ($V_{IN} = 5.5$ V)

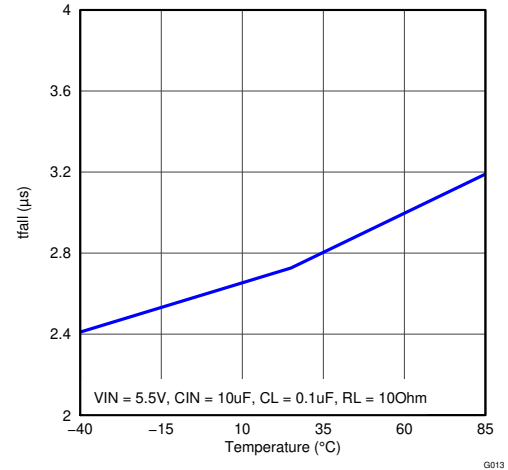


图 5-10. t_F vs Temperature ($V_{IN} = 5.5$ V)

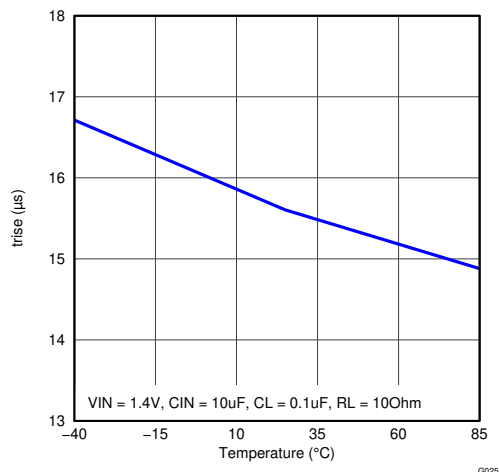


图 5-11. t_R vs Temperature ($V_{IN} = 1.4$ V)

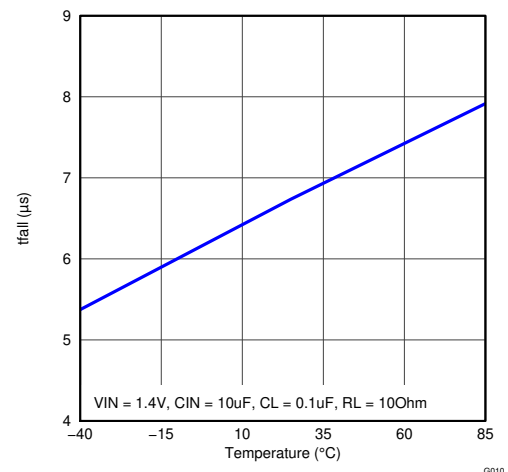


图 5-12. t_F vs Temperature ($V_{IN} = 1.4$ V)

5.7 Typical Characteristics (continued)

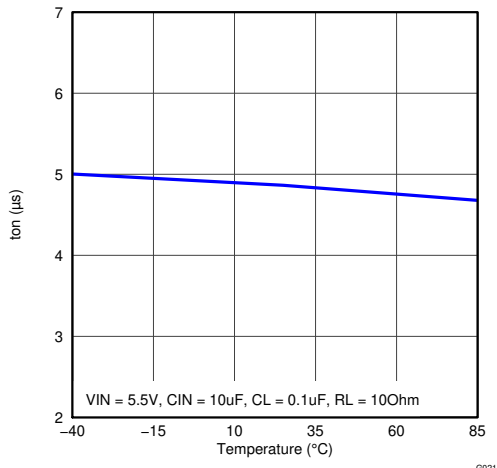


图 5-13. t_{ON} vs Temperature ($V_{IN} = 5.5\text{ V}$)

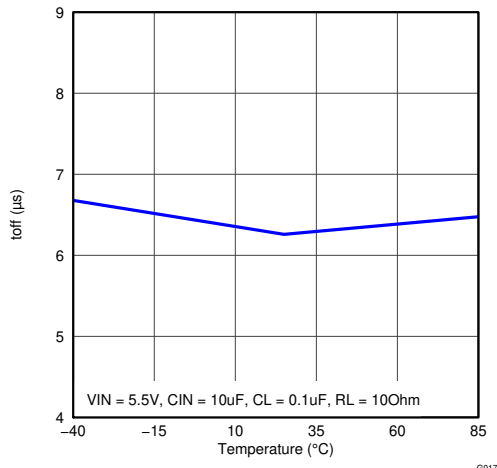


图 5-14. t_{OFF} vs Temperature ($V_{IN} = 5.5\text{ V}$)

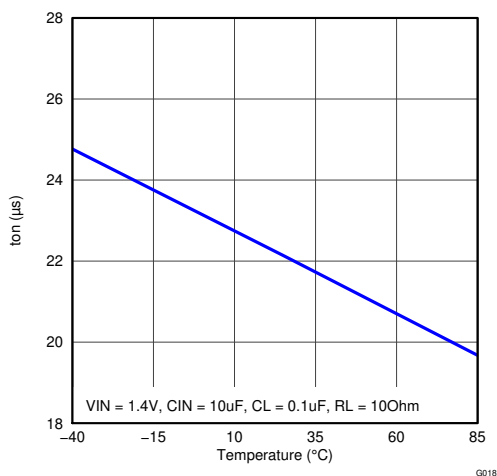


图 5-15. t_{ON} vs Temperature ($V_{IN} = 1.4\text{ V}$)

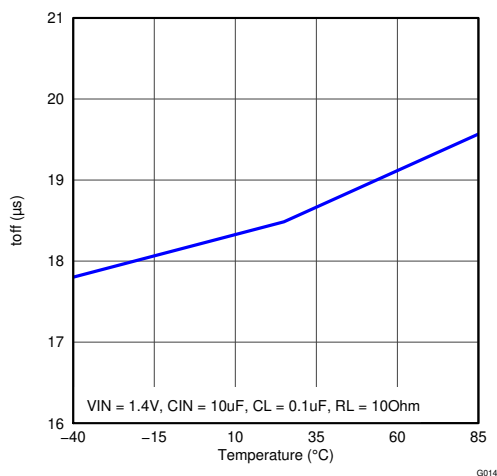


图 5-16. t_{OFF} vs Temperature ($V_{IN} = 1.4\text{ V}$)

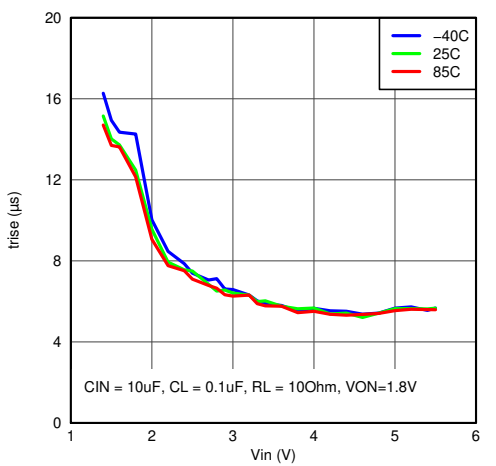


图 5-17. t_R vs V_{IN}

5.7.1 Typical AC Scope Captures at $T_A = 25^\circ\text{C}$

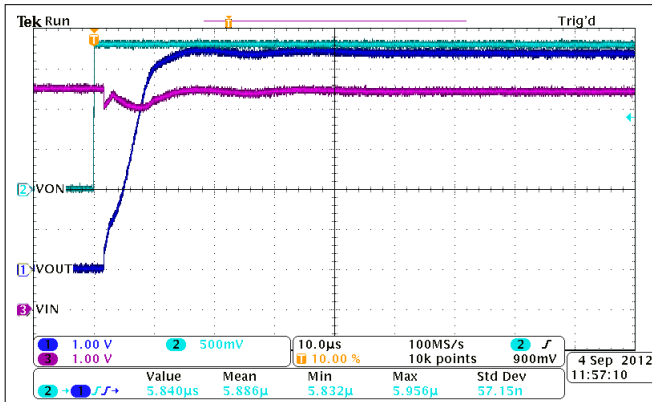


图 5-18. Turn-On Response Time ($V_{IN} = 5.5\text{ V}$, $C_{IN} = 10\text{ }\mu\text{F}$, $C_L = 1\text{ }\mu\text{F}$, $R_L = 10\text{ }\Omega$)

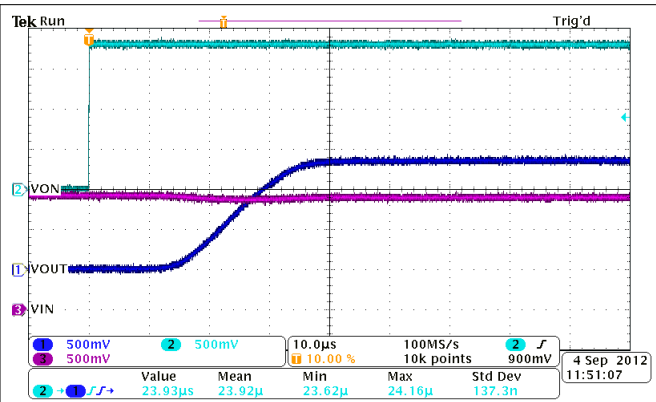


图 5-19. Turn-On Response Time ($V_{IN} = 1.4\text{ V}$, $C_{IN} = 10\text{ }\mu\text{F}$, $C_L = 1\text{ }\mu\text{F}$, $R_L = 10\text{ }\Omega$)

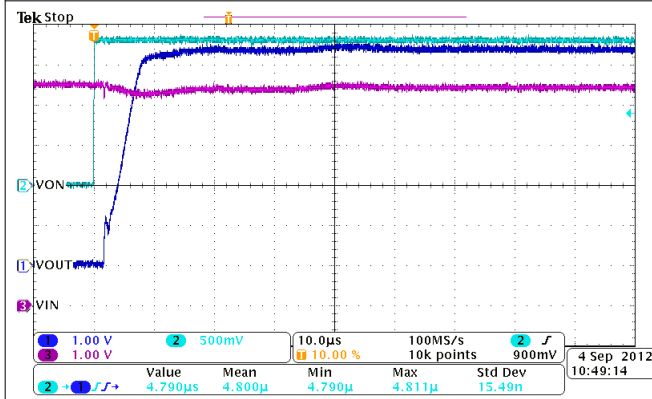


图 5-20. Turn-On Response Time ($V_{IN} = 5.5\text{ V}$, $C_{IN} = 10\text{ }\mu\text{F}$, $C_L = 0.1\text{ }\mu\text{F}$, $R_L = 10\text{ }\Omega$)

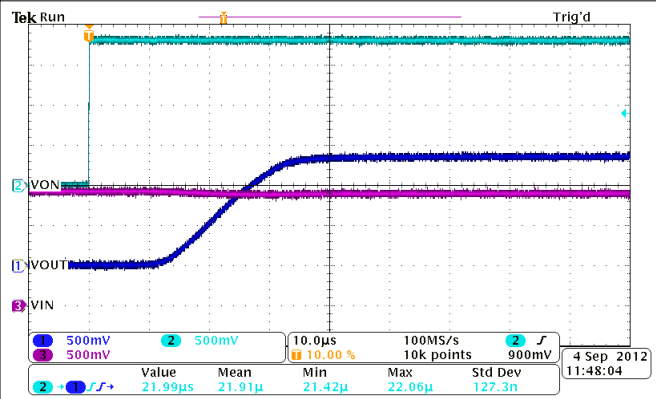


图 5-21. Turn-On Response Time ($V_{IN} = 1.4\text{ V}$, $C_{IN} = 10\text{ }\mu\text{F}$, $C_L = 0.1\text{ }\mu\text{F}$, $R_L = 10\text{ }\Omega$)

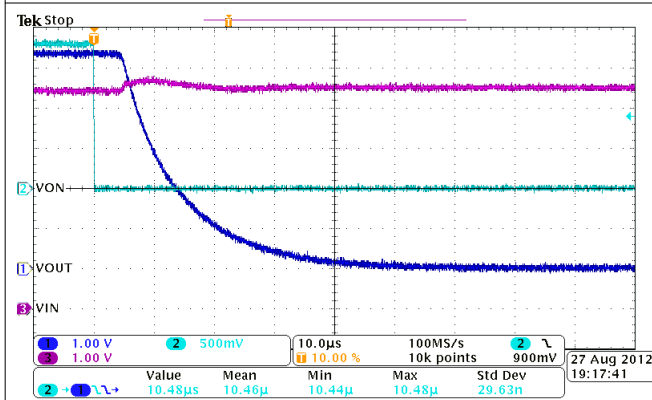


图 5-22. Turn-Off Response Time ($V_{IN} = 5.5\text{ V}$, $C_{IN} = 10\text{ }\mu\text{F}$, $C_L = 1\text{ }\mu\text{F}$, $R_L = 10\text{ }\Omega$)

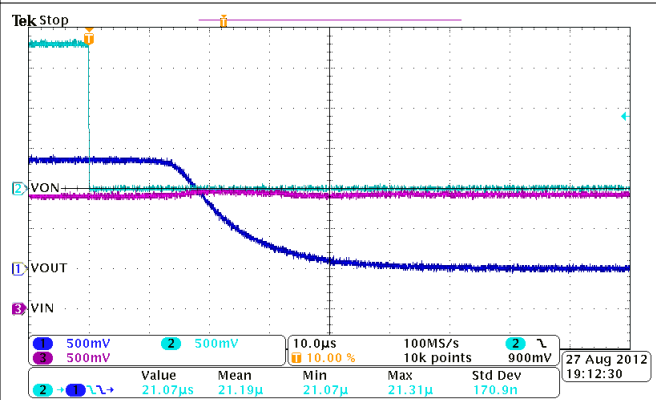
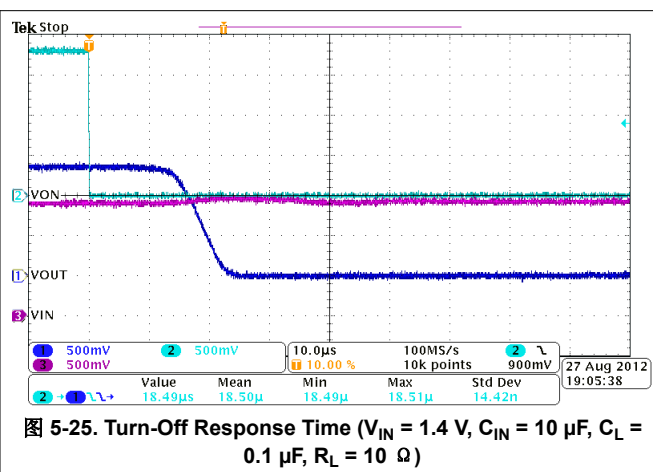
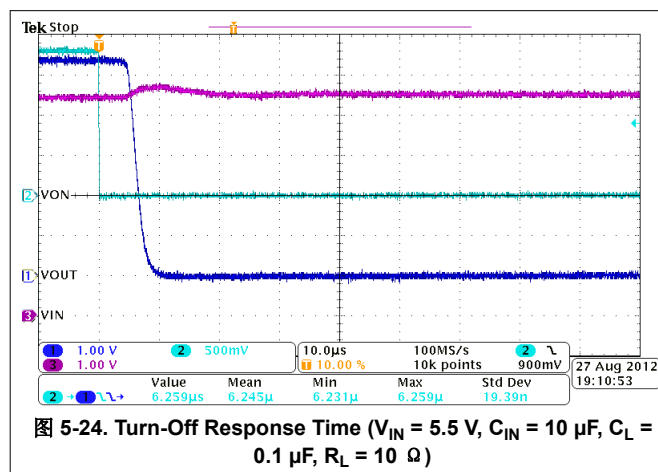


图 5-23. Turn-Off Response Time ($V_{IN} = 1.4\text{ V}$, $C_{IN} = 10\text{ }\mu\text{F}$, $C_L = 1\text{ }\mu\text{F}$, $R_L = 10\text{ }\Omega$)

5.7.1 Typical AC Scope Captures at $T_A = 25^\circ\text{C}$ (continued)



6 Pin Configuration and Functions

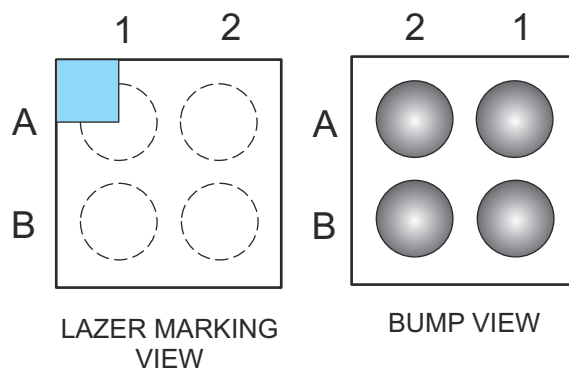


图 6-1. YZV Package 4-Pin DSBGA Bottom View

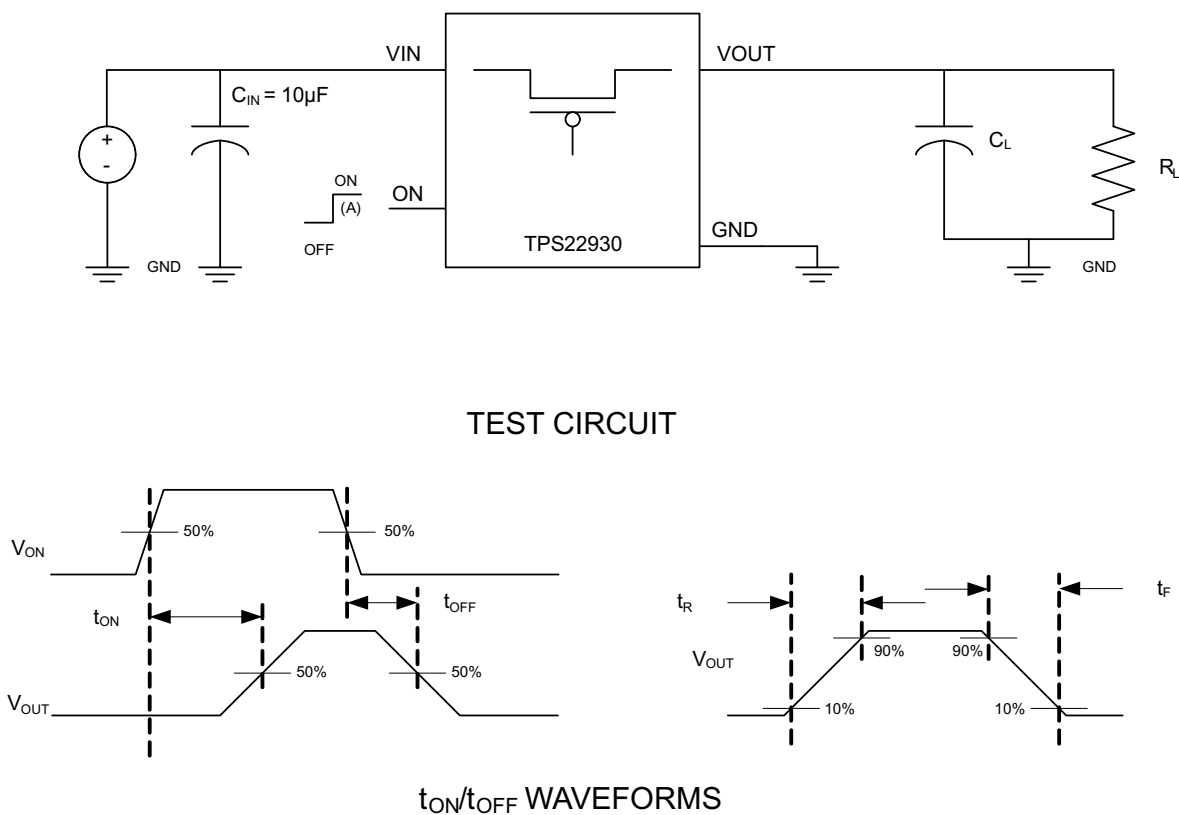
表 6-1. Pin Assignments

A	VOUT	VIN
B	GND	ON
	1	2

表 6-2. Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
A1	VOUT	O	Switch output.
A2	VIN	I	Switch input. Input bypass capacitor recommended for minimizing V_{IN} dip during transients.
B1	GND	–	Device ground.
B2	ON	I	Switch control input, active high. Do not leave floating.

7 Parameter Measurement Information



(A) Rise and fall times of the control signal are 100ns.

图 7-1. Test Circuit and t_{ON}/t_{OFF} Waveforms

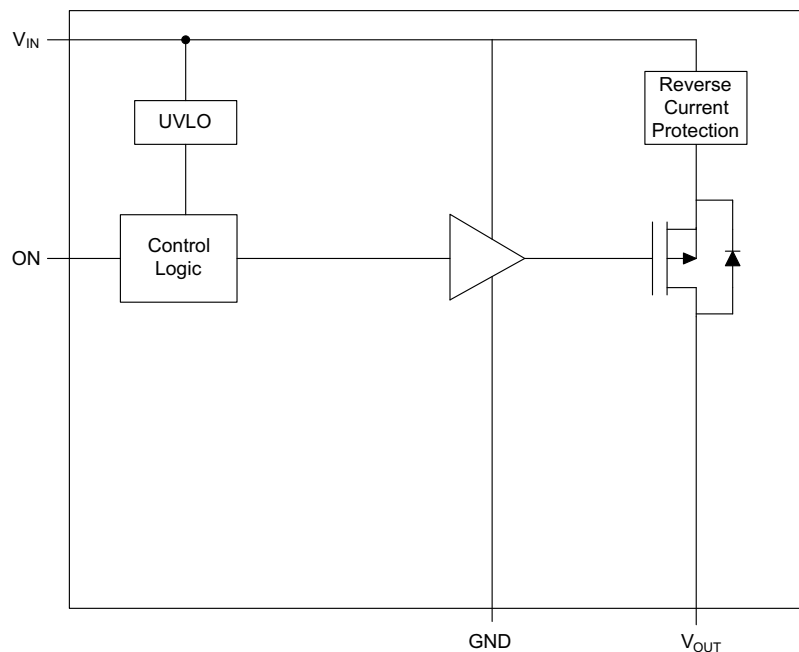
8 Detailed Description

8.1 Overview

The TPS22930 is a single channel, 2-A load switch in a 4-terminal BSGA package. A low enable threshold makes it capable of interfacing directly with low voltage control signals. In the off state, the device has very low leakage current during off state. This prevents downstream circuits from pulling high standby current from the supply. When turning on, the output will rise with a controlled slew rate to limit inrush current.

The device will also disengage the body diode when disabled to provide reverse current protection. The undervoltage lockout (UVLO) threshold will ensure the switch is turned off and will block reverse current if the V_{IN} power supply is removed.

8.2 Functional Block Diagram



8.3 Feature Description

表 8-1. Feature List

DEVICE	R_{ON} (TYP) AT 4.2 V	RISE TIME AT 4.2 V (TYP)	QUICK OUTPUT DISCHARGE ⁽¹⁾	MAXIMUM CONTINUOUS CURRENT	ENABLE
TPS22930A	35 m Ω	5.4 μ s	No	2 A	Active High

(1) This feature discharges output of the switch to GND through a resistor, preventing the output from floating when the pass FET is disabled.

8.3.1 On And Off Control

The ON pins control the state of the switch. Asserting ON high enables the switch. ON is active high and has a low threshold, making it capable of interfacing with low-voltage signals. The ON pin is compatible with standard GPIO logic threshold. It can be used with any microcontroller with 1.2V or higher GPIO voltage.

8.3.2 UVLO

UVLO turns off the switch if the input voltage drops below the under voltage lockout threshold. With the ON pin active, the input voltage rising above the under voltage lockout threshold will allow a controlled turn-on of the switch to limit current over-shoot.

The maximum UVLO of the TPS22930A is 1.2 V. This is under the minimum V_{IN} voltage and meets the system UVLO requirements. Once the device is disabled through UVLO, it will block reverse current in the case a voltage is applied to V_{OUT}

8.3.3 Reverse Current Protection

Reverse current protection (RCP) is only active when ON is asserted low. When ON is asserted high, current can flow from VOUT to VIN or from VIN to VOUT. This allows the device to function as a bi-directional switch when enabled.

8.4 Device Functional Modes

表 8-2 describes the state of the switch and the reverse current protection as determined by the ON pin.

表 8-2. Switch and Reverse Current Protection State

ON	V_{IN} to V_{OUT}	RCP
H	On	Off
L	Off	On

9 Application and Implementation

Note

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

9.1 Application Information

9.1.1 Input Capacitor (Optional)

To limit the voltage drop on the input supply caused by transient in-rush currents when the switch turns on into a discharged load capacitor or short-circuit, it is recommended that a capacitor be placed between V_{IN} and GND. A 1- μ F ceramic capacitor, C_{IN} , placed close to the pins, is usually sufficient. Higher values of C_{IN} can be used to further reduce the voltage drop during high-current application. When switching heavy loads, it is recommended to have an input capacitor about 100 times higher than the output capacitor to avoid excessive voltage drop; however, a 100 to 1 ratio is not required for proper functionality of the device.

9.1.2 Output Capacitor (Optional)

Due to the integrated body diode in the PMOS switch, a C_{IN} greater than C_L is highly recommended. A C_L greater than C_{IN} can cause V_{OUT} to exceed V_{IN} when the system supply is removed. This could result in current flow through the body diode from V_{OUT} to V_{IN} . A C_{IN} to C_L ratio of 100 to 1 is recommended for minimizing V_{IN} dip caused by inrush currents during startup; however, a 100 to 1 ratio is not required for proper functionality of the device.

9.2 Typical Application

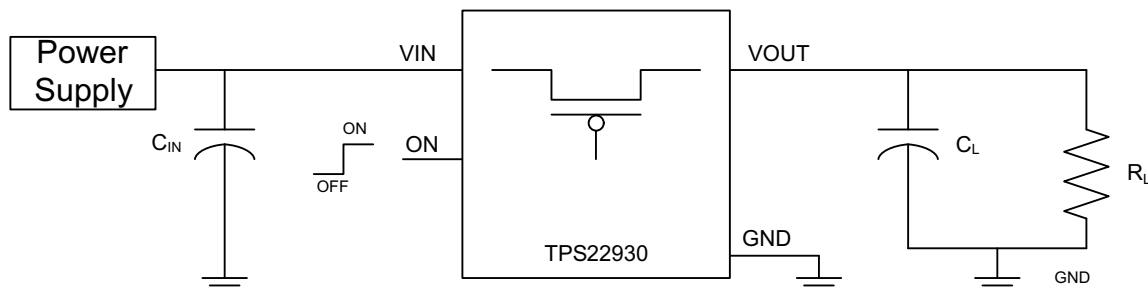


图 9-1. Typical Application Schematic

9.2.1 Design Requirements

For this design example, the following will be used as the system requirements.

表 9-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
V_{IN} Range	1.5 V to 5.5 V
UVLO Threshold	< 1.5 V
Reverse Current Protection	Required
Load Current	1 A
Ambient Temperature	25 °C

9.2.2 Detailed Design Procedure

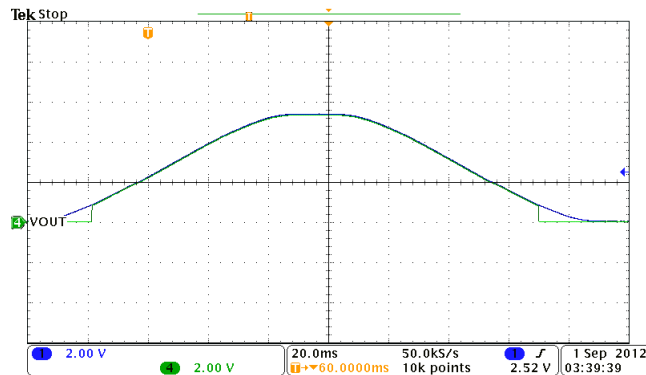
To begin the design process, the designer needs to know the following:

- Input Voltage range
- UVLO Threshold
- Load Current

- Ambient Temperature

9.2.3 Application Curve

图 9-2 shows the UVLO response when the device is enabled.



ON = 5 V

图 9-2. UVLO Response

10 Power Supply Recommendations

The device is designed to operate from a VIN range of 1.5 V to 5.5 V. The power supply should be well regulated and placed as close to the device terminals as possible. It must be able to withstand all transient and load current steps. In most situations, using an input capacitance of 1 μ F is sufficient to prevent the supply voltage from dipping when the switch is turned on. In cases where the power supply is slow to respond to a large transient current or large load current step, additional bulk capacitance may be required on the input.

11 Layout

11.1 Layout Guidelines

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effects that parasitic trace inductances may have on normal operation. Using wide traces for VIN, VOUT, and GND helps minimize the parasitic electrical effects along with minimizing the case to ambient thermal impedance. The ON pin cannot be left floating and must be driven either high or low for proper functionality.

图 11-1 shows an example of a layout.

11.2 Layout Example

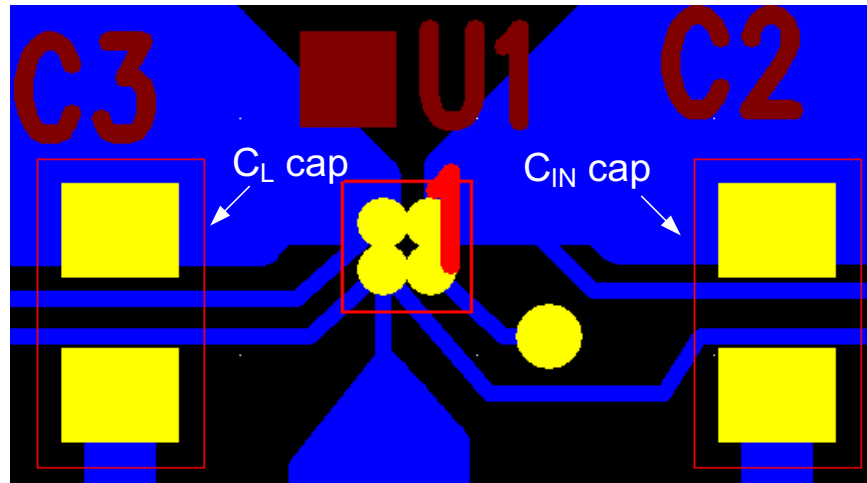


图 11-1. Layout Recommendation

11.3 Thermal Considerations

The maximum IC junction temperature should be restricted to 125°C under normal operating conditions. To calculate the maximum allowable dissipation, $P_{D(max)}$ for a given output current and ambient temperature, use the following equation as a guideline:

$$P_{D(max)} = \frac{T_{J(max)} - T_A}{\theta_{JA}} \quad (1)$$

where

- $P_{D(max)}$ = maximum allowable power dissipation
- $T_{J(max)}$ = maximum allowable junction temperature (125°C for the TPS22930)
- T_A = ambient temperature of the device
- θ_{JA} = junction to air thermal impedance. See [Thermal Information](#) table. This parameter is highly dependent upon board layout.

The power dissipated by the device depends on the R_{ON} of the device at a given V_{IN} . To calculate the amount of power being dissipated by the device, use the following equation:

$$P_{IR} = I^2 \times R_{ON} \quad (2)$$

where

- P_{IR} = power dissipated by the device
- I = load current in amperes
- R_{ON} = resistance of the device in Ohms at a given V_{IN} (see [Electrical Characteristics](#) table)

The result from [方程式 2](#) should always be less than or equal to the result from [方程式 1](#).

12 Device and Documentation Support

12.1 接收文档更新通知

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12.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

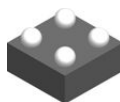
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.5 术语表

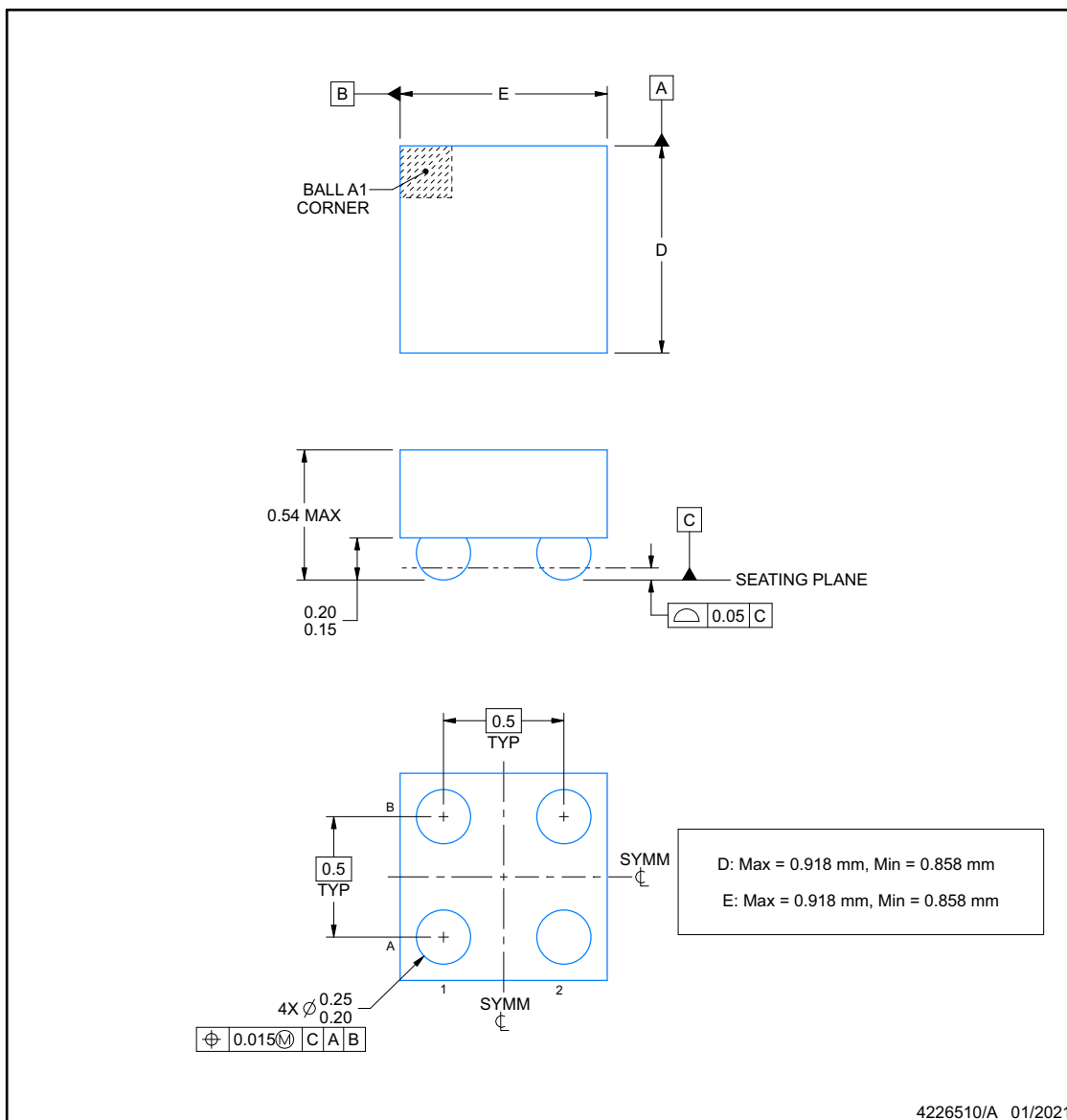
TI 术语表 本术语表列出并解释了术语、首字母缩略词和定义。

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**YZV0004-C01****PACKAGE OUTLINE****DSBGA - 0.54 mm max height**

DIE SIZE BALL GRID ARRAY

**NOTES:**

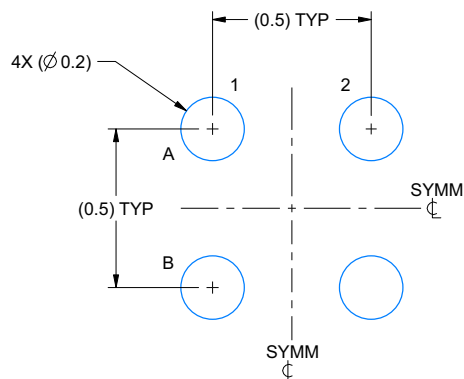
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

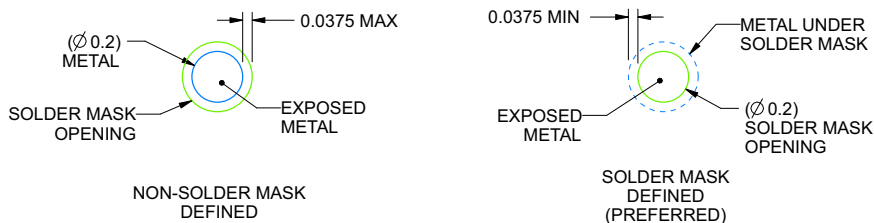
YZV0004-C01

DSBGA - 0.54 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 50X



SOLDER MASK DETAILS
NOT TO SCALE

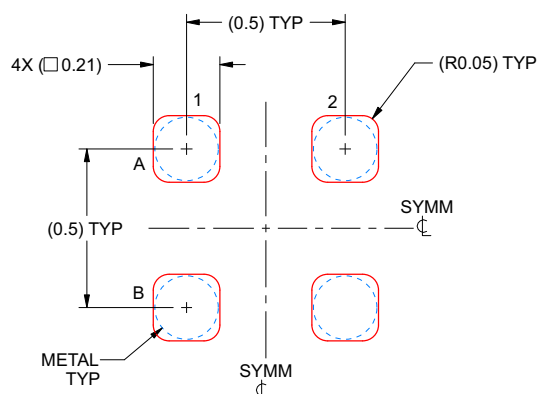
4226510/A 01/2021

NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN**YZV0004-C01****DSBGA - 0.54 mm max height**

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
 BASED ON 0.075 mm THICK STENCIL
 SCALE: 50X

4226510/A 01/2021

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS22930AYZVR	Active	Production	DSBGA (YZV) 4	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	3Q
TPS22930AYZVR.A	Active	Production	DSBGA (YZV) 4	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	3Q
TPS22930AYZVR.B	Active	Production	DSBGA (YZV) 4	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	3Q
TPS22930AYZVT	Active	Production	DSBGA (YZV) 4	250 SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	3Q
TPS22930AYZVT.A	Active	Production	DSBGA (YZV) 4	250 SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	3Q
TPS22930AYZVT.B	Active	Production	DSBGA (YZV) 4	250 SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	3Q

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

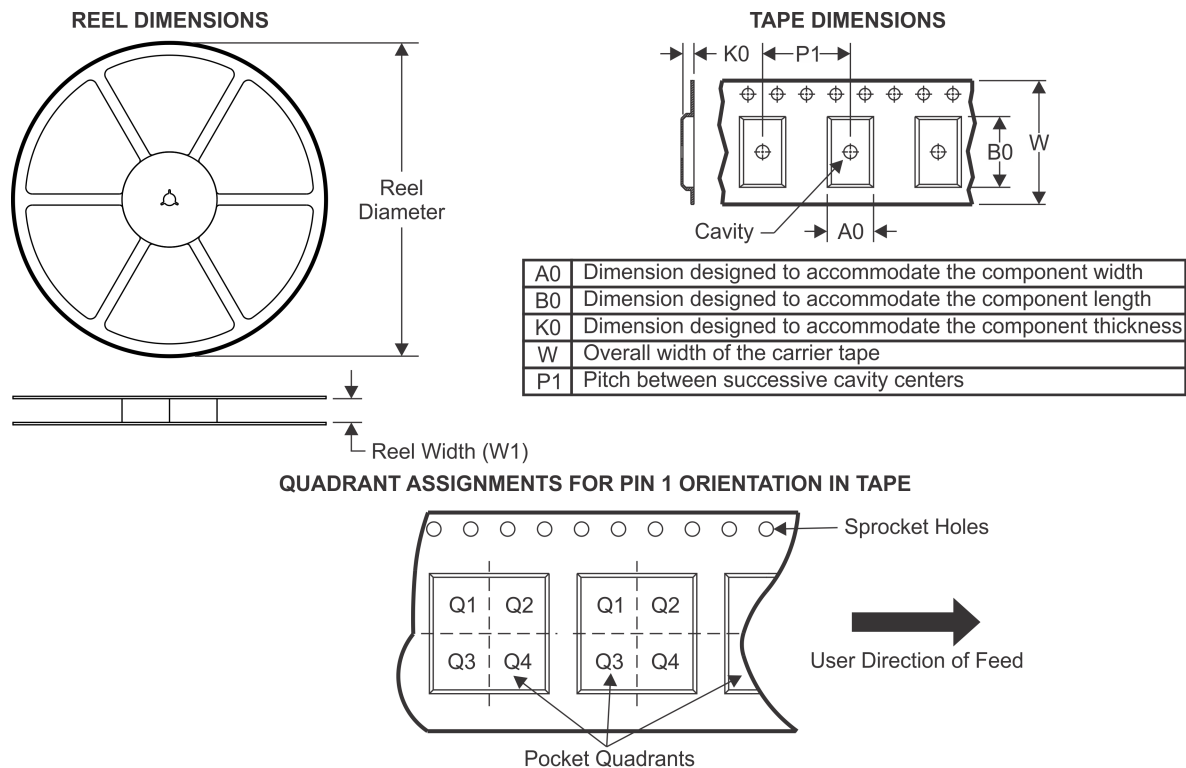
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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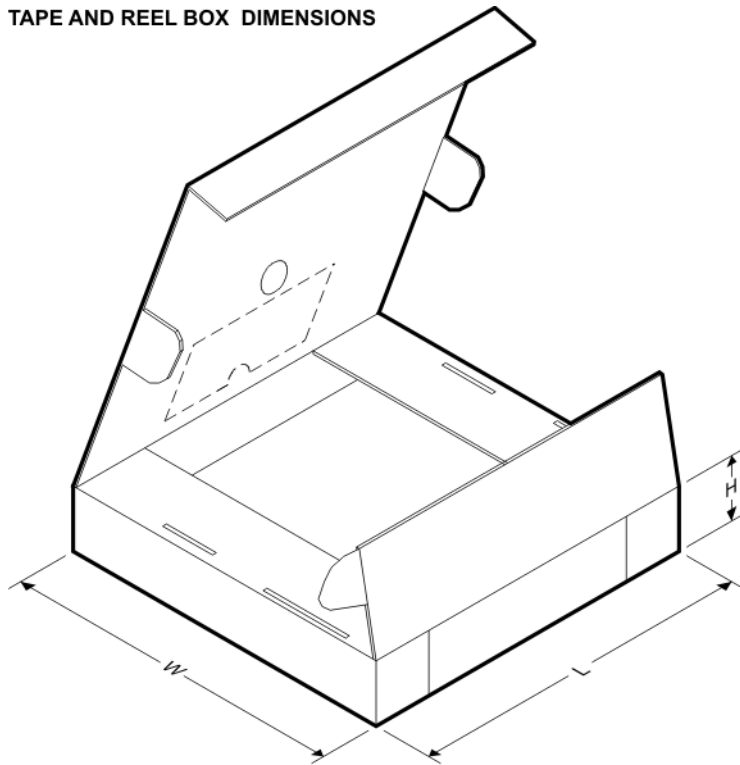
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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS22930AYZVR	DSBGA	YZV	4	3000	180.0	8.4	1.0	1.0	0.63	4.0	8.0	Q1
TPS22930AYZVT	DSBGA	YZV	4	250	180.0	8.4	1.0	1.0	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS22930AYZVR	DSBGA	YZV	4	3000	182.0	182.0	20.0
TPS22930AYZVT	DSBGA	YZV	4	250	182.0	182.0	20.0

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